

In the Claims:

Claim 1 (currently amended). A method of producing a wafer product, which comprises:

outputting a first wafer sheet with a sugar content of at least 23% or an equivalent content of a sugar substitute from a baking oven ~~at an elevated temperature;~~

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applying a layer of a food product to the first wafer sheet, ~~while the first wafer sheet is at the elevated temperature, a layer of a food product;~~

providing a second wafer sheet with a sugar content of at least 23% or an equivalent content of a sugar substitute, and placing the second wafer sheet, ~~while the second wafer sheet is at the elevated temperature,~~ on the first wafer sheet; and

subsequently compressing the first and second wafer sheets and shaping the first and second wafer sheets containing the layer of the food product ~~at the elevated temperature~~ while the first and second wafer sheets are maintained in a warm state sufficient to have an elasticity enabling said first and second wafer sheets to be shaped.

Claim 2 (previously amended). The method according to claim 1, which comprises placing onto the first wafer sheet the food product selected from the group consisting of a confection,

meat product, fish product, cheese product, fruit product, vegetable product, nuts, and almonds.

Claim 3 (previously amended). The method according to claim 1, wherein the sugar substitute is trehalose.

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Claim 4 (original). The method according to claim 1, which comprises cutting the pressed-together wafer sheets into individual hollow bodies and subsequently introducing a filling into the hollow bodies.

Claim 5 (previously amended). The method according to claim 1, which comprises, subsequent to the pressing step, cutting the shaped wafer product into individual wafer products and providing the individual wafer products with an outer coating.

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Claim 6 (currently amended). The method according to claim 1, which comprises processing, together with the first and second wafer sheets, additional wafer sheets at the elevated temperature each in a warm state sufficient to have an elasticity enabling said wafer sheets to be shaped with interposed layers of food products.

Claims 7-13 (withdrawn).